

Electronic Patent Application Fee Transmittal

Application Number:	10807417
Filing Date:	23-Mar-2004
Title of Invention:	Microcap wafer bonding apparatus
First Named Inventor/Applicant Name:	R. Shane Fazzio
Filer:	Thomas F. Woods
Attorney Docket Number:	10030899-1

Filed as Large Entity

Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 2 months with \$0 paid	1252	1	490	490

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				490